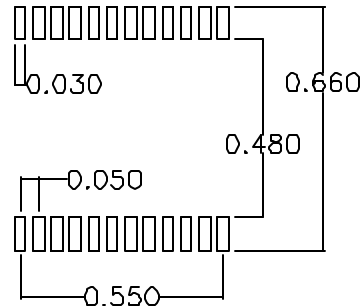
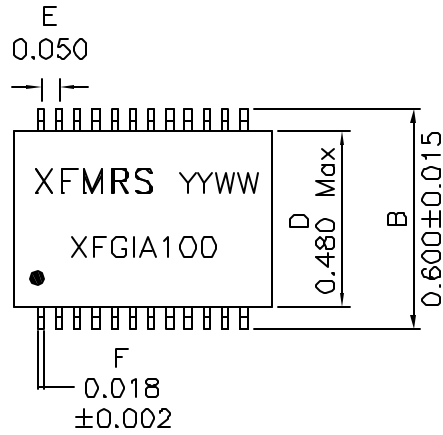
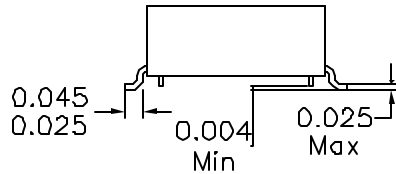
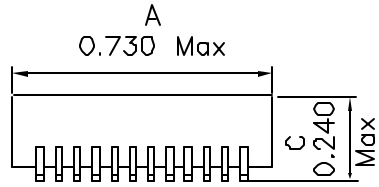
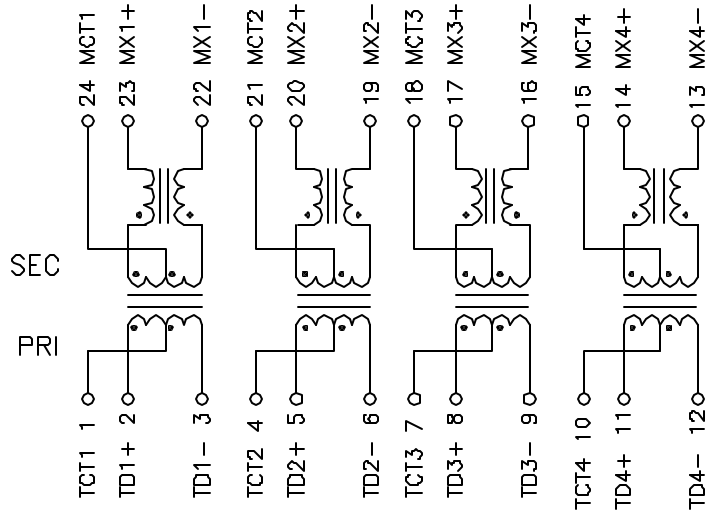


1. Mechanical Dimensions:



SUGGESTED PAD LAYOUT

2. Schematic:



DOC REV: B/2

3. Electrical Specifications: @25°C

- ISOLATION: 1500Vrms
- URNS RATIO: (PRI/SEC) 1CT:1CT ±2%
- SEC OCL: 350uH Min @100KHz 100mV, 8mAdc
- Rise Time: 1.75ns Max.
- INSERTION LOSS: -1.0dB MAX @1MHz-80MHz
- 1.1dB MAX @80-100MHz
- 1.5dB MAX @100-125MHz
- RETURN LOSS: 18dB Min @1-10MHz
- 15dB Min @30MHz
- 12dB Min @80MHz
- 10dB Min @100MHz
- Common to Common Rejection:
 - 60dB Min @1MHz
 - 40dB Min @30MHz
 - 35dB Min @80MHz
 - 30dB Min @100MHz
- CMRR: -30dB Min @1-60MHz
- Crosstalk: -40dB Min @1-30MHz
- 30dB Min @100MHz

Notes:

1. Solderability: Leads shall meet MIL-STD-202C, Method 208B for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen Index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004*(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

XFMRS Inc www.XFMRs.com		Title: 1000BASE-T Modules	
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XFGIA100		REV. B
	DWN.	Juan Mao	May-05-08
SCALE 2:1 SHT 1 OF 1	CHK.	YK Liao	May-05-08
	APP.	BW	May-05-08